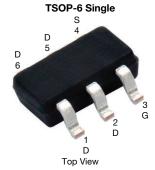
Si3129DV

www.vishay.com

Vishay Siliconix



Marking Code: BU

PRODUCT SUMMARY					
V _{DS} (V)	-80				
$R_{DS(on)}$ max. (Ω) at V_{GS} = -10 V	0.0827				
$R_{DS(on)}$ max. (Ω) at V_{GS} = -4.5 V	0.1242				
Q _g typ. (nC)	5.6				
I _D (A) ^a	-5.4				
Configuration	Single				

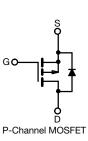
FEATURES

P-Channel 80 V (D-S) MOSFET

- TrenchFET® power MOSFET
- 100 % R_g tested
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Power management for portable and consumer
 - Load switches
 - DC/DC converters



ORDERING INFORMATION	
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Package	TSOP-6 Single
Lead (Pb)-free and halogen-free	Si3129DV-T1-GE3

PARAMETER	SYMBOL	LIMIT	UNIT		
Drain-source voltage		V _{DS}	-80	V	
Gate-source voltage		V _{GS}	±20	v	
	T _C = 25 °C		-5.4		
Continuous ducin ourrent (T 150 °C)	T _C = 70 °C		-4.4		
Continuous drain current (T _J = 150 °C)	T _A = 25 °C	I _D	-3.8 ^{b, c}		
	T _A = 70 °C		-3.0 ^{b, c}		
Pulsed drain current (t = 300 µs)		I _{DM}	-20	А	
Ocationa como ducio dicale comont	T _C = 25 °C		-3.5		
Continuous source-drain diode current	T _A = 25 °C	I _S	-1.7 ^{b, c}	7	
Single pulse evelopele energy		I _{AS}	15		
Single pulse avalanche energy	L = 0.1 mH	E _{AS}	11		
	T _C = 25 °C		4.2		
Maximum power dissipation	T _C = 70 °C	D	2.7	w	
	T _A = 25 °C	P _D	2 ^{b, c}	VV	
	T _A = 70 °C		1.3 ^{b, c}		
Operating junction and storage temperature rai	T _J , T _{stq}	-55 to 150	°C		

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT	
Maximum Junction-to-Ambient b, d	t ≤ 5 s	R _{thJA}	45	62.5	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	25	30	0/10	

Notes

a. T_C = 25 °C

b. Surface mounted on 1" x 1" FR4 board

c. t = 5 s

d. Maximum under steady state conditions is 110 °C/W

S20-0813-Rev. A, 19-Oct-2020

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Pb-free



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Si3129DV

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static						
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, \text{ I}_{D} = -250 \mu\text{A}$	-80	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_J$	I _D = -10 mA	-	-115	-	
V _{GS(th)} temperature coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA	-	4.8	-	mV/°C
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = -250 \ \mu A$	-1.5	-	-2.5	V
Gate-source leakage	I _{GSS}	V_{DS} = 0 V, V_{GS} = ± 20 V	-	-	± 100	nA
Zere gete voltage drein ourrent		V_{DS} = -80 V, V_{GS} = 0 V	-	-	-10	
Zero gate voltage drain current	IDSS	V_{DS} = -80 V, V_{GS} = 0 V, T_{J} = 55 °C	-	-	-50	μA
On-state drain current ^a	I _{D(on)}	$V_{DS} \leq$ -5 V, V_{GS} = -10 V	-5	-	-	А
Drain-source on-state resistance ^a	Р	V_{GS} = -10 V, I _D = -3.8 A	- 0.0689 0.08		0.0827	
Drain-source on-state resistance ~	R _{DS(on)}	$V_{GS} = -4.5 \text{ V}, \text{ I}_{D} = -3.1 \text{ A}$	-	0.0994	0.1242	Ω
Dynamic ^b						
Input capacitance	Ciss		-	805	-	
Output capacitance	C _{oss}	V_{DS} = -40 V, V_{GS} = 0 V, f = 1 MHz	-	265	-	pF
Reverse transfer capacitance	C _{rss}		-	10	-	
Total acto charge	0	V_{DS} = -40 V, V_{GS} = -10 V, I_{D} = -3.8 A	-	12	18	nC
Total gate charge	Qg		-	5.6	8.4	
Gate-source charge	Q _{gs}	V_{DS} = -40 V, V_{GS} = -4.5 V, I_D = -3.8 A	-	3.1	-	
Gate-drain charge	Q _{gd}		-	1.4	-	
Gate resistance	Rg	f = 1 MHz	0.8	4.4	8.8	Ω
Turn-on delay time	t _{d(on)}		-	15	30	
Rise time	tr	V_{DD} = -40 V, R_{L} = 13.3 Ω	-	8	16]
Turn-off delay time	t _{d(off)}	$I_D\cong$ -3 A, V_{GEN} = - 10 V, R_g = 1 Ω	-	25	50	
Fall time	t _f		-	12	24	
Turn-on delay time	t _{d(on)}		-	28	56	ns
Rise time	tr	V_{DD} = -40 V, R_L = 13.3 Ω	-	42	84	
Turn-off delay time	t _{d(off)}	$\text{I}_\text{D}\cong$ -3 A, V_GEN = - 4.5, R_g = 1 Ω	-	24	48	
Fall time	t _f		-	15	30	
Drain-Source Body Diode Characterist	tics					
Continuous source-drain diode current	ls	T _C = 25 °C	-	-	-3.5	^
Pulse diode forward current	I _{SM}		-	-	-20	A
Body diode voltage	V _{SD}	$I_{\rm S} = -3$ A, $V_{\rm GS} = 0$ V	-	-0.8	-1.2	V
Body diode reverse recovery time	t _{rr}		-	38	57	ns
Body diode reverse recovery charge	Q _{rr}		-	50	75	nC
Reverse recovery fall time	ta	l _F = -3 A, dl/dt = 100 A/μs, T _J = 25 °C	-	26	-	
Reverse recovery rise time	t _b		-	12	-	ns

Notes

a. Pulse test; pulse width $\leq 300~\mu\text{s},~\text{duty}~\text{cycle} \leq 2~\%$

b. Guaranteed by design, not subject to production testing

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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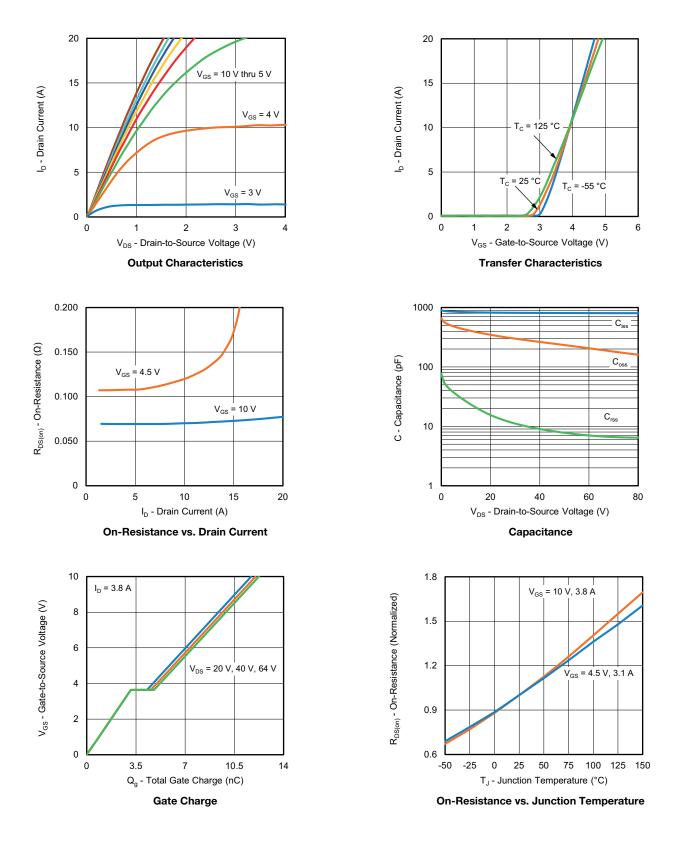
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Si3129DV

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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



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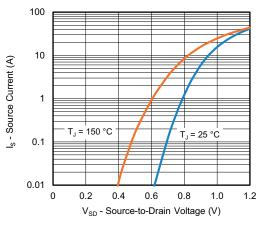
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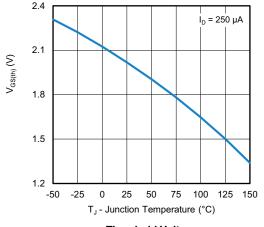
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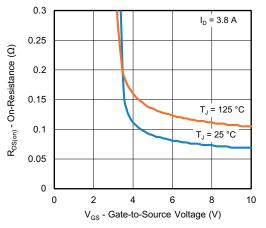
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



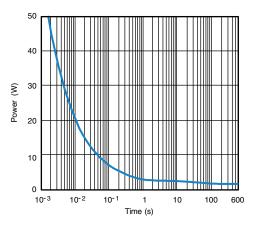
Source-Drain Diode Forward Voltage



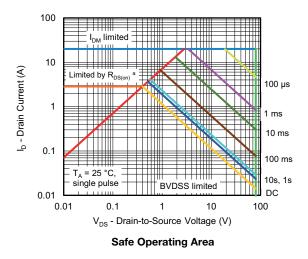




On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient



Note

a. V_{GS} > minimum V_{GS} at which R_{DS(on)} is specified

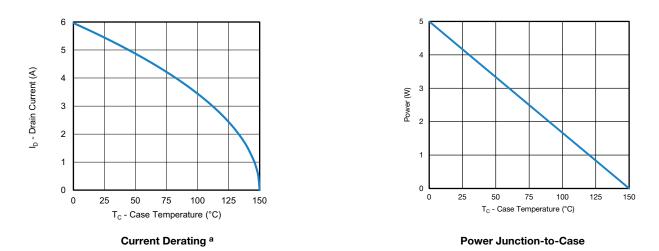
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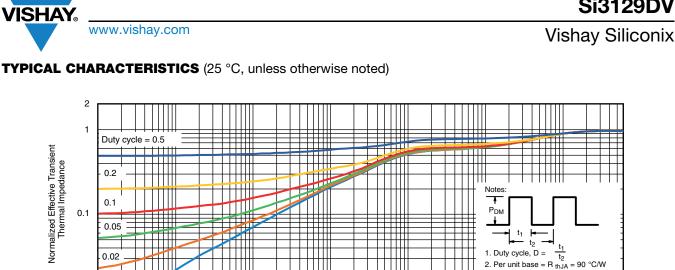
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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Note

a. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit

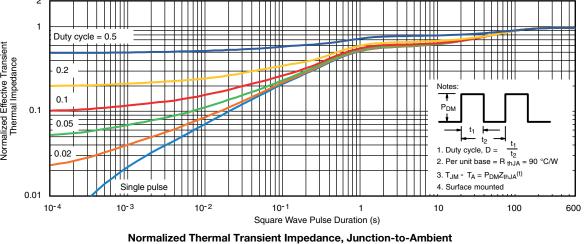


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Si3129DV





2 1 Duty cycle = 0.5 Normalized Effective Transient Thermal Impedance 0.2 0.1 0.1 0.05 0.02 Single pulse 0.01 10⁻³ 10-4 10⁻² 10⁻¹ 1 10 Square Wave Pulse Duration (s)

Normalized Thermal Transient Impedance, Junction-to-Foot



Package Information

Vishay Siliconix

TSOP: 5/6-LEAD JEDEC Part Number: MO-193C









6-LEAD TSOP



	MILLIMETERS			INCHES		
Dim	Min	Nom	Max	Min	Nom	Max
Α	0.91	-	1.10	0.036	-	0.043
A ₁	0.01	-	0.10	0.0004	-	0.004
A ₂	0.90	-	1.00	0.035	0.038	0.039
b	0.30	0.32	0.45	0.012	0.013	0.018
С	0.10	0.15	0.20	0.004	0.006	0.008
D	2.95	3.05	3.10	0.116	0.120	0.122
Е	2.70	2.85	2.98	0.106	0.112	0.117
E ₁	1.55	1.65	1.70	0.061	0.065	0.067
е	0.95 BSC		0.0374 BSC			
e ₁	1.80	1.90	2.00	0.071	0.075	0.079
L	0.32	-	0.50	0.012	-	0.020
L ₁		0.60 Ref			0.024 Ref	
L ₂	0.25 BSC				0.010 BSC	
R	0.10	-	-	0.004	-	-
θ	0°	4°	8°	0°	4°	8°
θ_1	7° Nom				7° Nom	
ECN: C DWG: 5		ev. I, 18-Dec	c-06			

PAD Pattern



Vishay Siliconix

Recommended Land Pattern For TSOP-5L / TSOP-6L





TSOP 5L





Note

• All dimensions are in inches (millimeter)

ECN: C22-0860-Rev. B, 24-Oct-2022	
DWG: 3010	

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